### VLSI DESIGN

VII Semester: ECE										
Course Code	Category	Hours / Week			Credits	Maximum Marks				
AECB27	Core	L	T	P	С	CIA	SEE	Total		
		3	-	-	3	30	70	100		
Contact Classes: 45	Tutorial Classes: Nil	Practical Classes: Nil				Total Classes: 45				

### I. COURSE OVERVIEW:

This course introduces the students the fabrication techniques of design and implementation of very large scale (VLSI) circuits. Specific topics include: CMOS logic, MOSFET theory, design rules & layout procedures and logic and circuit simulations. The course further gives information on data path subsystems, PLD's performance parameters and testing approaches for the circuits.

### **II. OBJECTIVES:**

### The course should enable the students to:

- I The aspects of hierarchical VLSI design from the metal oxide semiconductor transistor up to the system level, fabrication and testing.
- II The subsystem design incorporating into a VLSI chip with contemporary techniques for achieving high-speed, low-power and low area overhead.
- III Advanced modern tools such as vivado and cadence for front end and back end forchip design through a practical approach.

### III. COURSE OUTCOME:

### After successful completion of the course, students should be able to:

- CO 1 Summarize the MOSFET fabrication process, electrical properties, scaling for analyzing Understand reliability issues and understanding latest trends in VLSI.
- CO 2 **Develop** the stick diagrams, layouts of MOS circuits using lambda, absolute and Euler Apply physical design rules.
- CO 3 **Describe** inverters, complex gates and dynamic CMOS circuits in terms of power Understand consumption, distortion and speed of operation
- CO 4 Explain data path subsystems and array subsystems using stickdiagrams and layouts. Apply
- CO 5 **Outline** the role of Programmable logic devices for realization of complex boolean Understand functions.
- CO 6 **Examine** the test strategies, implementation approach on full custom and semi custom Analyze design for speed, cost, reconfiguration and reliability parameters.

### IV. SYLLABUS:

MODULE-I	INTRODUCTION TO MOS TRANSISTORS		Classes:09
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MOS Transistors, CMOS Logic, CMOS Fabrication and Layout, Design Partitioning, Fabrication, Packaging, and Testing, MOS transistor Theory, Long Channel I-V Characteristics, C-V Characteristics, Non-Ideal I-V Effects, DC Transfer Characteristics

MODULE-II	PRINCIPLES OF CIRCUIT DESIGN	Classes:09
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CMOS Processing Technology, CMOS Technologies, Layout Design Rules, CMOS Process Enhancements, Technology-Related CAD Issues, Manufacturing Issues, Circuit Simulation, A SPICE Tutorial, Device Models, Device Characterization, Circuit Characterization, Interconnect Simulation. Combinational Circuit Design, Circuit Families, Silicon-On-Insulator Circuit Design, Sub Threshold Circuit Design. Sequential Circuit Design, Circuit Design of Latches and Flip-Flops, Static Sequencing Element Methodology, Sequencing Dynamic Circuits, Synchronizers, Wave Pipelining

## **MODULE-III**

## **DESIGN METRICS AND SUB SYSTEM DESIGN**

Power, Sources of Power Dissipation, Dynamic Power, Static Power, Energy-Delay Optimization, Low Power Architectures, Robustness, Variability, Reliability, Scaling, Statistical Analysis of Variability, Variation-Tolerant Design. Delay, Transient Response, RC Delay Model, Linear Delay Model, Logical Effort of Paths, Timing Analysis Delay Models,

Datapath Subsystems, Addition/Subtraction, One/Zero Detectors, Comparators, Counters, Boolean Logical Operations, Coding, Shifters, Multiplication

### **MODULE-IV**

### **ROBUST DESIGN OF MEMORIES**

Classes: 09

Classes: 10

Array Subsystems, SRAM, DRAM, Read-Only Memory, Serial Access Memories, Content-Addressable Memory, Programmable Logic Arrays, Robust Memory Design, Special-Purpose Subsystems.

**MODULE-V** 

**TESTING** 

Classes: 08

Packaging and Cooling, Power Distribution, Clocks, PLLs and DLLs, I/O, High-Speed Links, Random Circuits, Design Methodology and Tools, Testing, Debugging, and Verification.

### **Text Books:**

- 1. Neil H.E. Weste, David Money Harris, "CMOS VLSI Design –A Circuits and Systems Perspective," Addision –Wesley, 2011
- 2. Jan M Rabey, "Digital Integrated Circuits," 2<sup>nd</sup>Edition, Pearson Education, 2003.
- 3. John F.Wakerly, "Digital Design Principles & Practices", 3<sup>rd</sup> Edition, 2005, PHI/ Pearson Education Asia,

### **Reference Books:**

- 1. Wang Alice, Calhoun Benton High smith, Chandrakasan Anantha P., "Sub-threshold Design for Ultra Low-Power Systems," Springer 2006
- 2. Pucknell, Kamran Eshraghian, "Basic VLSI Design," Third Edition, Prentice Hall of India, 2007.
- 3. R. Jacob Baker, Harry W.LI., David E.Boyee, "CMOS Circuit Design, Layout and Simulation", Wiley-IEEE Press, USA, 2005. ISBN: 978-0-470-88132-3
- 4. Calhoun, B., C. Schurgers, A. Wang, A. Chandrakasan, "Low Energy Digital Circuit Design," in *Hardware Technology Drivers of Ambient Intelligence*, editors Satyen Mukherjee, 2006 Springer.
- 5. Park, Synghyun, "Towards Low-Power yet High-Performance Networks-on-Chip," *Ph.D. Thesis*, Massachusetts Institute of Technology, September 2014.
- 6. Sinangil, Mahmut, "Low-Power and Application-Specific SRAM Design for Energy-Efficient Motion Estimation," *Ph.D. Thesis* Massachusetts Institute of Technology, June 2012
- 7. Amirtharajah, Rajeevan, "Design of Low Power VLSI Systems Powered by Ambient Mechanical Vibration," *Ph.D. Thesis*, Massachusetts Institute of Technology, May 1999.

# **Web References:**

- 1 http://dspace.mit.edu/handle/1721.1/93776
- 2 http://dspace.mit.edu/handle/1721.1/75650
- 3 https://engineering.purdue.edu/~vlsi/ECE559\_Fall09/?\_ga=2.120672008.1227662350.1573631317 316737531.1573631317
- 4 Class Notes: http://cobweb.ecn.purdue.edu/~vlsi/ECE559 Fall09

### **E-Text Books:**

- 1. https://www.springer.com/gp/book/9780387335155
- 2. http://swarm.cs.pub.ro/~mbarbulescu/SMPA/CMOS-VLSI-design.pdf